

20-3237

CLEAR FLEXIBLE EPOXY

DESCRIPTION:

20-3237 is a new 1:1 ratio, low viscosity *Epoxy Rubber* System designed for potting delicate electronic components requiring inspection. 20-3237 is an ideal candidate for applications requiring testing and/or repairs of embedded components. Cured material can be cut away to replace components and then repotted with fresh material.

20-3237 has low stress and shrinkage during polymerization. Its outstanding electrical properties, thermal shock and impact resistance make this system a good choice for many potting, bonding, and encapsulating applications.

FEATURES:

Flexible
Low viscosity
resistance

Excellent impact resistance
Excellent thermal shock

TYPICAL SPECIFICATIONS:

Viscosity @ 25°C, cps	
Resin	8,500
Catalyst	75
Specific Gravity @ 25°C	
Resin	1.15
Catalyst	1.00
Pot life, 100 gram mass, @ 25°C	8 Hours
Hardness, Shore A, 25°C	80
Tensile strength, psi	875
Elongation, %	165
Water absorption, %, 24 hours @ 25°C	0.9
Impact resistance, Izod ft. lb./in notch	2.0
Dielectric strength, volts/mil	420
Dielectric constant, 60 Hz	3.4
Dissipation factor, 60 Hz	.02
Volume resistivity, ohm-cm	1.0 x 10 ¹³



INSTRUCTIONS FOR USE:

1. By weight or volume thoroughly mix equal parts resin to catalyst.
2. Pour and follow one of the following cure schedules:
 - a) 25°C 24-36 Hours
 - b) 60°C 12 Hours
 - c) 90°C 2-4 Hours

IMPORTANT:

The information in this brochure is based on data obtained by our own research and is considered accurate. However, no warranty is expressed or implied regarding the accuracy of these data, the results to be obtained from the use thereof, or that any such use will not infringe any patent. This information is furnished upon the condition that the person receiving it shall make his own tests to determine the suitability thereof for his particular purpose.